

# Quad 2-Input NAND Gate with Schmitt-Trigger Inputs

## High-Performance Silicon-Gate CMOS

### MC74HC132A

The MC74HC132A is identical in pinout to the LS132. The device inputs are compatible with standard CMOS outputs; with pull-up resistors, they are compatible with LSTTL outputs.

The HC132A can be used to enhance noise immunity or to square up slowly changing waveforms.

#### Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0  $\mu$ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements as Defined by JEDEC Standard No. 7A
- Chip Complexity: 72 FETs or 18 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

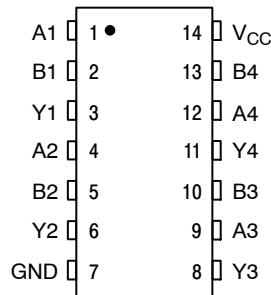
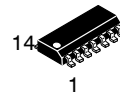
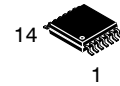
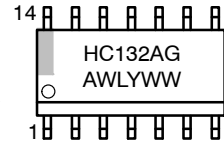


Figure 1. Pin Assignment

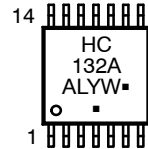
#### MARKING DIAGRAMS



SOIC-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G



A = Assembly Location  
L, WL = Wafer Lot  
Y, YY = Year  
W, WW = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

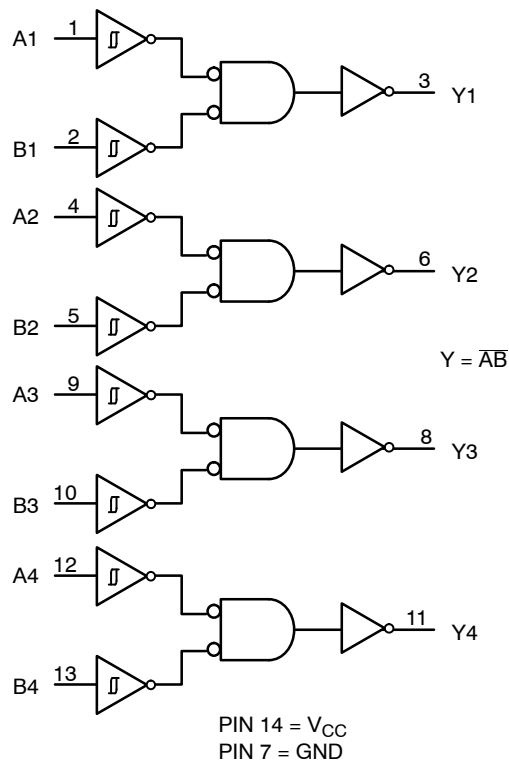
#### FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	H
L	H	H
H	L	H
H	H	L

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

## MC74HC132A



**Figure 2. Logic Diagram**

### ORDERING INFORMATION

Device	Package	Shipping†
MC74HC132ADG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74HC132ADR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC74HC132ADTG	TSSOP-14 (Pb-Free)	96 Units / Rail
MC74HC132ADTR2G	TSSOP-14 (Pb-Free)	2500 / Tape & Reel
NLV74HC132ADG*	SOIC-14 (Pb-Free)	55 Units / Rail
NLV74HC132ADR2G*	SOIC-14 (Pb-Free)	2500 / Tape & Reel
NLV74HC132ADTG*	TSSOP-14 (Pb-Free)	96 Units / Rail
NLV74HC132ADTR2G*	TSSOP-14 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

# MC74HC132A

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
$V_{CC}$	Positive DC Supply Voltage	-0.5 to +7.0	V
$V_{IN}$	Digital Input Voltage	-0.5 to $V_{CC}+0.5$	V
$V_{OUT}$	DC Output Voltage	-0.5 to $V_{CC}+0.5$	V
$I_{IK}$	Input Diode Current	$\pm 20$	mA
$I_{OK}$	Output Diode Current	$\pm 20$	mA
$I_{OUT}$	DC Output Current, per Pin	$\pm 25$	mA
$I_{CC}$	DC Supply Current, $V_{CC}$ and GND Pins	$\pm 75$	mA
$I_{GND}$	DC Ground Current per Ground Pin	$\pm 75$	mA
$T_{STG}$	Storage Temperature Range	-65 to +150	$^{\circ}C$
$T_L$	Lead Temperature, 1 mm from Case for 10 Seconds	260	$^{\circ}C$
$T_J$	Junction Temperature Under Bias	+150	$^{\circ}C$
$\theta_{JA}$	Thermal Resistance	14-SOIC 14-TSSOP	125 170 $^{\circ}C/W$
$P_D$	Power Dissipation in Still Air at 85 $^{\circ}C$	SOIC TSSOP	500 450 mW
MSL	Moisture Sensitivity	Level 1	
$F_R$	Flammability Rating	Oxygen Index: 30% - 35%	UL 94 V0 @ 0.125 in
$V_{ESD}$	ESD Withstand Voltage	Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	> 2000 > 100 > 500 V
$I_{Latch-Up}$	Latch-Up Performance	Above $V_{CC}$ and Below GND at 85 $^{\circ}C$ (Note 4)	$\pm 300$ mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Tested to EIA/JESD22-A114-A.
2. Tested to EIA/JESD22-A115-A.
3. Tested to JESD22-C101-A.
4. Tested to EIA/JESD78.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
$V_{IN}, V_{OUT}$	DC Input Voltage, Output Voltage (Referenced to GND)	0	$V_{CC}$	V
$T_A$	Operating Temperature, All Package Types	-55	+125	$^{\circ}C$
$t_r, t_f$	Input Rise and Fall Time (Figure 3)	-	No Limit (Note 5)	ns

5. When  $V_{IN} \sim 0.5 V_{CC}$ ,  $I_{CC} \gg$  quiescent current.
6. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

## DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	$V_{CC}$ V	Guaranteed Limit			Unit
				-55 $^{\circ}C$ to 25 $^{\circ}C$	$\leq 85^{\circ}C$	$\leq 125^{\circ}C$	
$V_{T+max}$	Maximum Positive-Going Input Threshold Voltage (Figure 5)	$V_{OUT} = 0.1 V$ $ I_{OUT}  \leq 20 \mu A$	2.0	1.5	1.5	1.5	V
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
$V_{T+min}$	Minimum Positive-Going Input Threshold Voltage (Figure 5)	$V_{OUT} = 0.1 V$ $ I_{OUT}  \leq 20 \mu A$	2.0	1.0	0.95	0.95	V
			4.5	2.3	2.25	2.25	
			6.0	3.0	2.95	2.95	
$V_{T-max}$	Maximum Negative-Going Input Threshold Voltage (Figure 5)	$V_{OUT} = V_{CC} - 0.1 V$ $ I_{OUT}  \leq 20 \mu A$	2.0	0.9	0.95	0.95	V
			4.5	2.0	2.05	2.05	
			6.0	2.6	2.65	2.65	

# MC74HC132A

## DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			Unit
				-55°C to 25°C	≤ 85°C	≤ 125°C	
V <sub>T_min</sub>	Minimum Negative-Going Input Threshold Voltage (Figure 5)	V <sub>OUT</sub> = V <sub>CC</sub> - 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	2.0	0.3	0.3	0.3	V
			4.5	0.9	0.9	0.9	
			6.0	1.2	1.2	1.2	
V <sub>H_max</sub> (Note 7)	Maximum Hysteresis Voltage (Figure 5)	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	2.0	1.2	1.2	1.2	V
			4.5	2.25	2.25	2.25	
			6.0	3.0	3.0	3.0	
V <sub>H_min</sub> (Note 7)	Minimum Hysteresis Voltage (Figure 5)	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	2.0	0.2	0.2	0.2	V
			4.5	0.4	0.4	0.4	
			6.0	0.5	0.5	0.5	
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>IN</sub> ≤ V <sub>T_min</sub> or V <sub>T_max</sub>  I <sub>OUT</sub>   ≤ 20 μA	2.0	1.9	1.9	1.9	V
		4.5	4.4	4.4	4.4		
		V <sub>IN</sub> ≤ -V <sub>T_min</sub> or V <sub>T_max</sub>  I <sub>OUT</sub>   ≤ 4.0 mA  I <sub>OUT</sub>   ≤ 5.2 mA	4.5	3.98	3.84	3.7	
		6.0	5.48	5.34	5.2		
V <sub>OL</sub>	Maximum Low-Level Output Voltage	V <sub>IN</sub> ≥ V <sub>T_max</sub>  I <sub>OUT</sub>   ≤ 20 μA	2.0	0.1	0.1	0.1	V
		4.5	0.1	0.1	0.1		
		V <sub>IN</sub> ≥ V <sub>T_max</sub>  I <sub>OUT</sub>   ≤ 4.0 mA  I <sub>OUT</sub>   ≤ 5.2 mA	4.5	0.26	0.33	0.4	
		6.0	0.26	0.33	0.4		
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0	±0.1	±1.0	±1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>IN</sub> = V <sub>CC</sub> or GND I <sub>OUT</sub> = 0 μA	6.0	1.0	10	40	μA

7. V<sub>H\_min</sub> > (V<sub>T\_max</sub>) - (V<sub>T\_min</sub>); V<sub>H\_max</sub> = (V<sub>T\_max</sub>) + (V<sub>T\_min</sub>).

# MC74HC132A

## AC ELECTRICAL CHARACTERISTICS ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6.0 \text{ ns}$ )

Symbol	Parameter	$V_{CC}$ V	Guaranteed Limit			Unit
			$-55^\circ\text{C}$ to $25^\circ\text{C}$	$\leq 85^\circ\text{C}$	$\leq 125^\circ\text{C}$	
$t_{PLH}$ , $t_{PHL}$	Maximum Propagation Delay, Input A or B to Output Y (Figures 3 and 4)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
$t_{TLH}$ , $t_{THL}$	Maximum Output Transition Time, Any Output (Figures 3 and 4)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
$C_{in}$	Maximum Input Capacitance	—	10	10	10	pF
$C_{PD}$	Power Dissipation Capacitance (per Gate) (Note 8)	Typical @ $25^\circ\text{C}$ , $V_{CC} = 5.0 \text{ V}$			pF	
		24				

8. Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

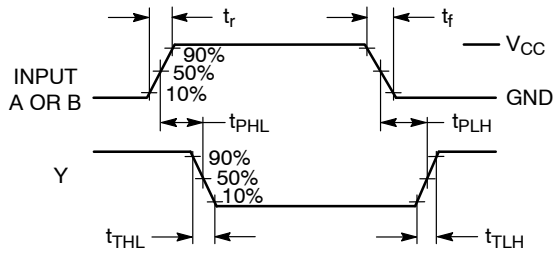
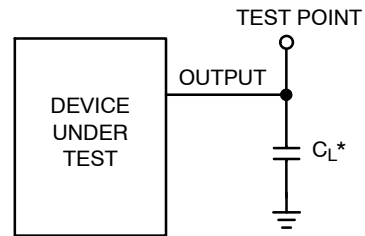


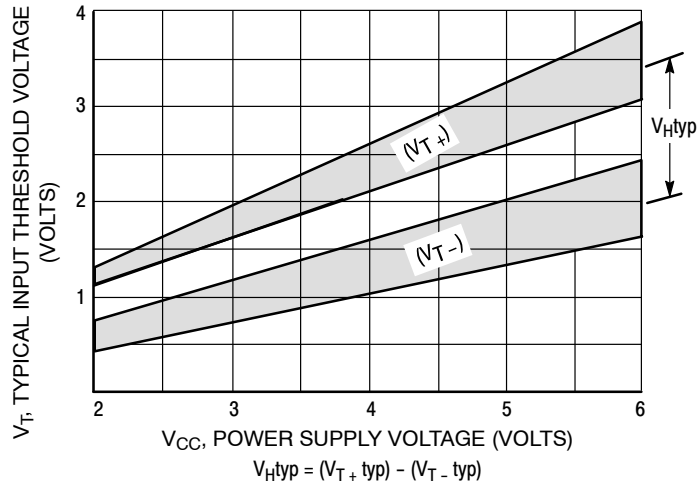
Figure 3. Switching Waveforms



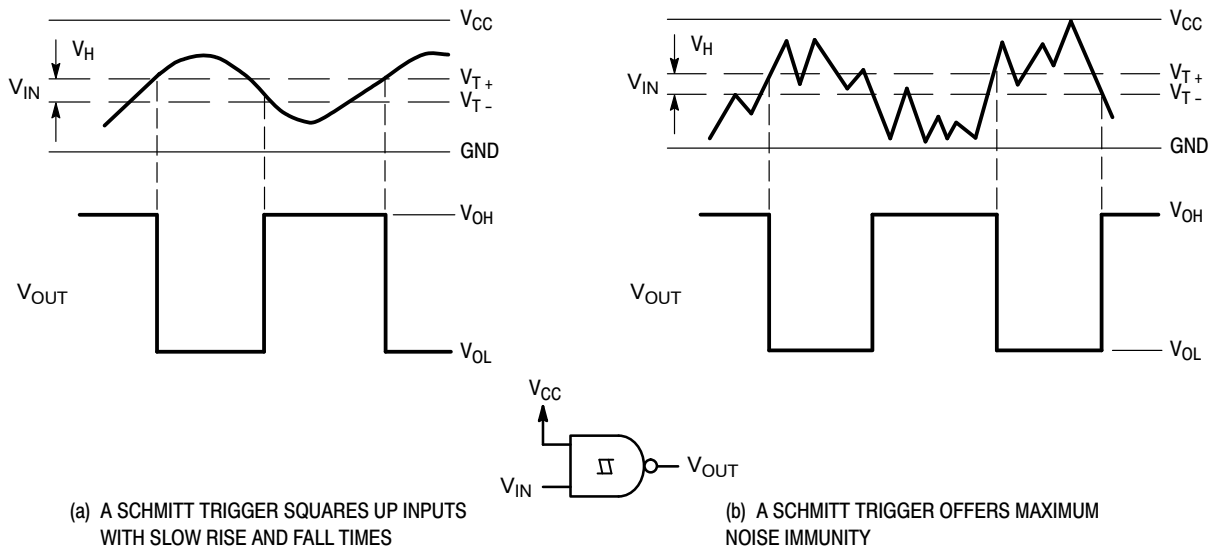
\*Includes all probe and jig capacitance

Figure 4. Test Circuit

# MC74HC132A



**Figure 5. Typical Input Threshold,  $V_{T+}$ ,  $V_{T-}$  Versus Power Supply Voltage**



**Figure 6. Typical Schmitt-Trigger Applications**

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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**SOIC-14**  
**CASE 751A-03**  
**ISSUE L**

DATE 03 FEB 2016

STYLE 1:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. NO CONNECTION  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 2:  
 CANCELLED

STYLE 3:  
 PIN 1. NO CONNECTION  
 2. ANODE  
 3. ANODE  
 4. NO CONNECTION  
 5. ANODE  
 6. NO CONNECTION  
 7. ANODE  
 8. ANODE  
 9. ANODE  
 10. NO CONNECTION  
 11. ANODE  
 12. ANODE  
 13. NO CONNECTION  
 14. COMMON CATHODE

STYLE 4:  
 PIN 1. NO CONNECTION  
 2. CATHODE  
 3. CATHODE  
 4. NO CONNECTION  
 5. CATHODE  
 6. NO CONNECTION  
 7. CATHODE  
 8. CATHODE  
 9. CATHODE  
 10. NO CONNECTION  
 11. CATHODE  
 12. CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 5:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. COMMON ANODE  
 8. COMMON CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 6:  
 PIN 1. CATHODE  
 2. CATHODE  
 3. CATHODE  
 4. CATHODE  
 5. CATHODE  
 6. CATHODE  
 7. CATHODE  
 8. ANODE  
 9. ANODE  
 10. ANODE  
 11. ANODE  
 12. ANODE  
 13. ANODE  
 14. ANODE

STYLE 7:  
 PIN 1. ANODE/CATHODE  
 2. COMMON ANODE  
 3. COMMON CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. COMMON CATHODE  
 12. COMMON ANODE  
 13. ANODE/CATHODE  
 14. ANODE/CATHODE

STYLE 8:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. COMMON ANODE  
 8. COMMON ANODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. NO CONNECTION  
 12. ANODE/CATHODE  
 13. ANODE/CATHODE  
 14. COMMON CATHODE

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TSSOP-14 WB  
CASE 948G  
ISSUE C

DATE 17 FEB 2016

SCALE 2:1



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

GENERIC MARKING DIAGRAM\*



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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